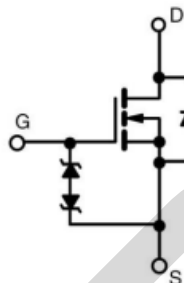


N-Channel Super Junction MOSFET

MCR65F105PT

TO-247

FRD MOSFET
ESD protect



V_{DS}	650	V
$R_{DS(on),TYP}$	95	mΩ
I_D	30	A

Features

- 1.Low on – resistance
- 2.Reduced Switching & Conduction Losses
- 3.Fast Recovery Body-Diode
- 4.Package TO-247

Applications

- 1.PC power
- 2.Telecom power
- 3.Server power
- 4.EV Charger
- 5.Motor driver

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Absolute Maximum Ratings

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	650	V
Drain Current –continuous @25°C	I_D	30	A
Pulsed Drain Current ¹	I_{DM}	105	A
Gate-Source Voltage	V_{GS}	±30	V
Single Pulse Avalanche ²	E_{AS}	1250	mJ
Operating Junction	T_j	-55 to 150	°C
Storage temperature	T_{stg}	-55 to 150	°C

Note:

1. Pulse width limited by maximum junction temperature.
2. $I_D = 6.2\text{A}$, $V_{DD} = 50\text{V}$, starting $T_J = 25^\circ\text{C}$.

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	650	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=650V, V_{GS}=0V$	--	--	20	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 30V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	3	4	5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=15A$	--	95	105	m Ω

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

C_{iss}	Input Capacitance	$V_{DS}=380V, V_{GS}=0V, f=100KHz$	--	3100	--	pF
C_{oss}	Output Capacitance		--	67	--	pF
C_{rss}	Reverse Transfer Capacitance		--	4.4	--	pF
Q_g	Total Gate Charge	$V_{DS}=380V, I_D=16A, V_{GS}=10V$	--	68	--	nC
Q_{gs}	Gate-Source Charge		--	14	--	nC
Q_{gd}	Gate-Drain Charge		--	25	--	nC

Switching Characteristics

$T_{d(on)}$	Turn-on Delay Time	$V_{DS}=380V, I_D=15A, R_G=4.7\Omega, V_{GS}=10V$	--	10	--	ns
T_r	Turn-on Rise Time		--	5	--	ns
$T_{d(off)}$	Turn-Off Delay Time		--	80	--	ns
T_f	Turn-Off Fall Time		--	14	--	ns

Source- Drain Diode Characteristics@ $T_j = 25^\circ\text{C}$ (unless otherwise stated)

I_s	Continuous Current		--	--	30	A
I_{sm}	Maximum pulsed drain to source diode forward current		--	--	105	A
V_{SD}	Forward Voltage	$V_{GS} = 0V$, $I_s = 15\text{ A}$	--	--	0.9	V
T_{rr}	Reverse Recovery Time	$V_R = 380\text{ V}$, $I_{SD} = 15\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$	--	185	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.4	--	μC
I_{mm}	Reverse recovery current		--	16	--	A
T_{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible(turn-on is dominated by $L_S + L_D$)				

Typical Performance Characteristics

Figure 1 . On- State Characteristics

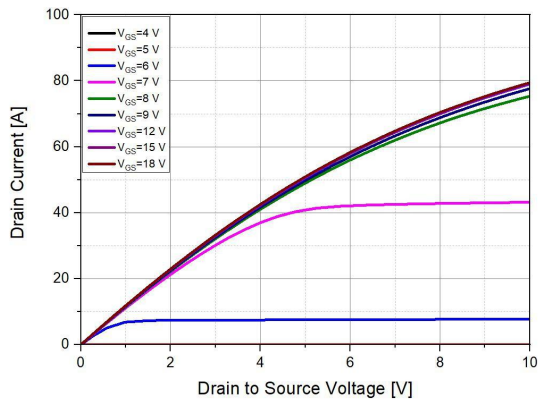


Figure 2 . Transfer Characteristics

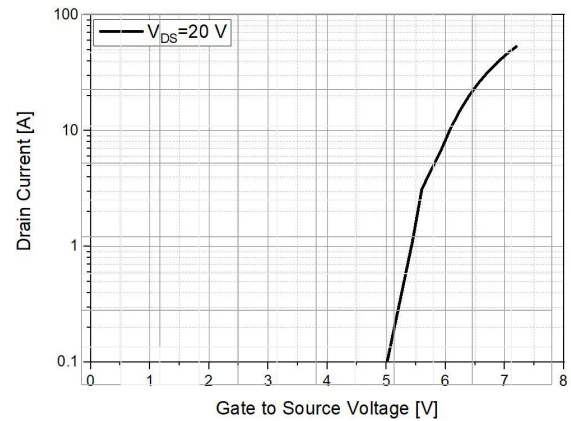


Figure 3 . On- Resistance Characteristics vs Drain Current and Gate Voltage

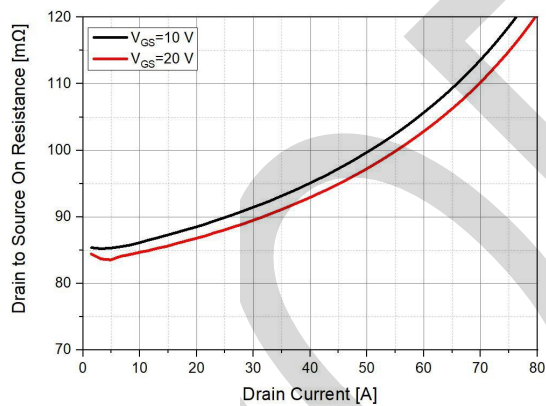


Figure 4 . On- State Characteristics Current vs Doide forward Voltage

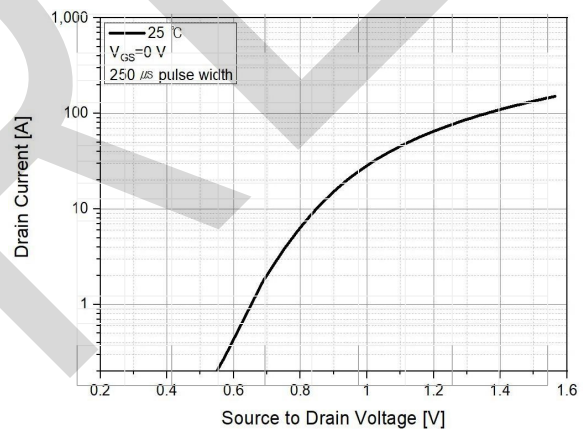


Figure 5 . Capacitance Characteristics

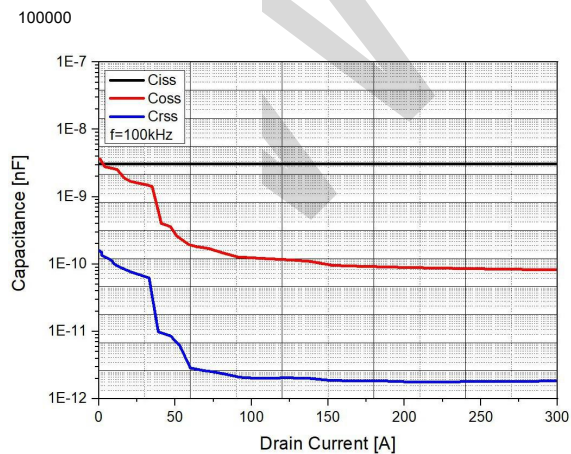
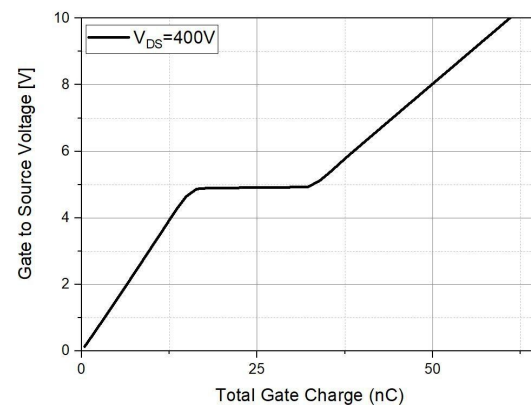


Figure 6 . Gate Charge Characteristics



Typical Performance Characteristics

Figure 7 . Drain to Source Resistance vs Gate to Source voltage

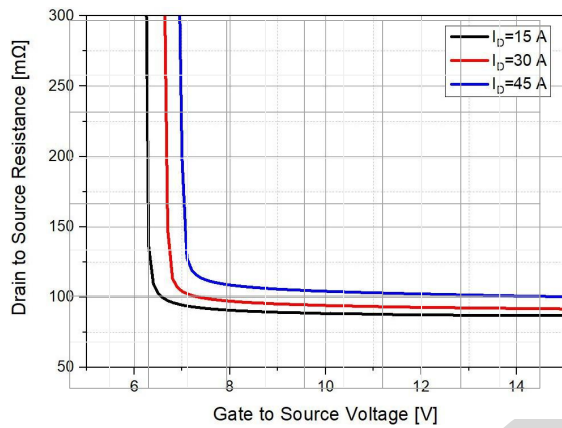


Figure 8 . Drain to Source Resistance vs Gate to Source voltage

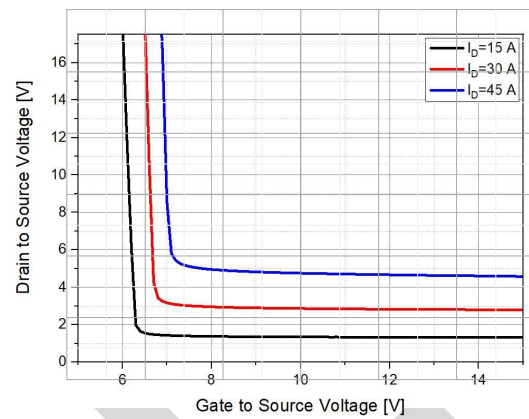
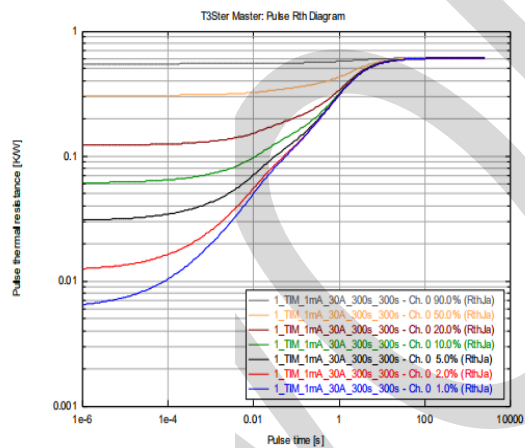
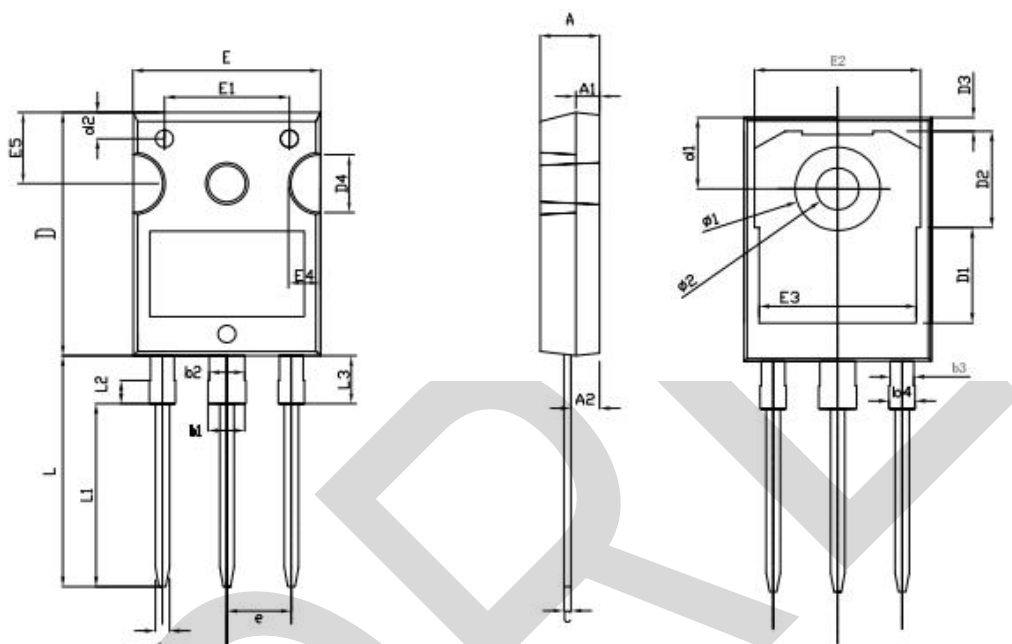


Figure 9 . Transient thermal response

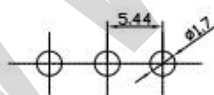


PACKAGE OUTLINE DIMENSIONS

TO-247



RECOMMENDED LAND PATTERN



UNIT: mm

	MIN	NOM	MAX
A	4.85	5.00	5.15
A1	1.90	2.00	2.10
A2	2.27	2.41	2.54
b	1.10	1.20	1.30
b1	2.90	-	3.20
b2	2.90	3.00	3.10
b3	1.90	2.00	2.10
b4	2.00	-	2.20
c	0.55	0.60	0.68
D	20.80	21.00	21.10
D1	-	8.23	-
D2	-	8.32	-
D3	-	1.17	-
D4	3.68	4.90	5.10
d1	6.04	6.15	6.30
d2	2.20	2.30	2.40
E	15.70	15.80	16.00
E1	-	10.50	-
E2	-	14.02	-
E3	-	13.50	-
E4	2.20	2.40	2.60
E5	5.49	5.80	6.00
e	5.34	5.44	5.54
L	19.72	19.92	20.12
L1	-	15.79	-
L2	-	1.98	-
L3	4.00	4.10	4.47
φ1	7.10	7.19	7.30
φ2	3.50	3.60	3.70